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(57) **ABSTRACT**

The present invention relates to a substrate processing apparatus for processing a substrate. The substrate processing apparatus (1) includes a controller (90). The controller (90) rotates the substrate (W) at a second speed, after rotating the substrate (W) at a first speed. The controller (90) supplies a dry fluid from a dry fluid nozzle (30) onto the substrate (W) for predetermined time after rotating the substrate (W) at the second speed, and while rotating the substrate (W) at a third speed. The controller (90) moves a dry fluid nozzle (30) from a center of the substrate (W) toward a peripheral portion of the substrate (W) while continuing to supply the dry fluid from the dry fluid nozzle (30).

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